

GTM CORPORATION

ISSUED DATE :2005/03/28
REVISED DATE :2006/12/12B

GL3055

N-CHANNEL ENHANCEMENT MODE POWER MOSFET

BVDSS	30V
RDS(ON)	26mΩ
ID	4A

Description

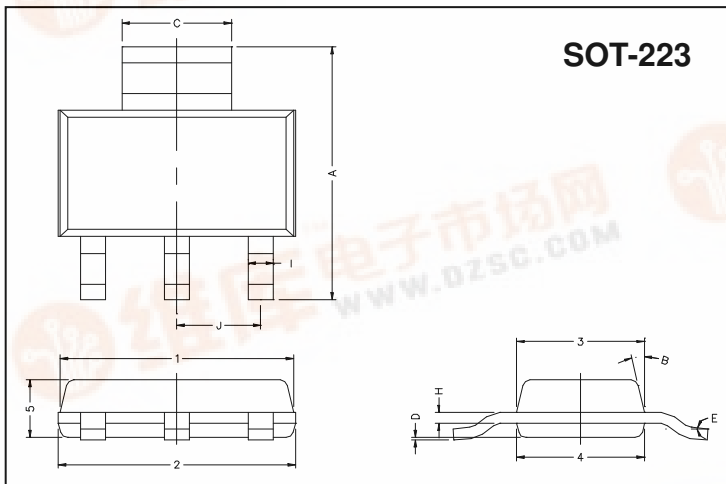
The GL3055 provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The SOT-223 package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

Features

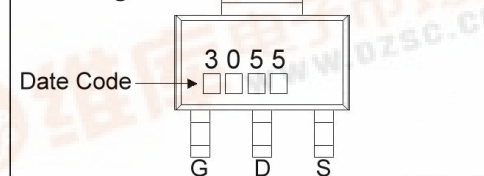
- *Dynamic dv/dt Rating
- *Simple Drive Requirement
- *Repetitive Avalanche Rated
- *Fast Switching

Package Dimensions



SOT-223

Marking :



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	6.70	7.30	B	13°TYP.	
C	2.90	3.10	J	2.30 REF.	
D	0.02	0.10	1	6.30	6.70
E	0°	10°	2	6.30	6.70
I	0.60	0.80	3	3.30	3.70
H	0.25	0.35	4	3.30	3.70
			5	1.40	1.80

Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current, $V_{GS}@10V$	$I_D @T_A=25^{\circ}C$	4.0	A
Continuous Drain Current, $V_{GS}@10V$	$I_D @T_A=70^{\circ}C$	3.2	A
Pulsed Drain Current ¹	I_{DM}	20	A
Total Power Dissipation	$P_D @T_A=25^{\circ}C$	2.7	W
Linear Derating Factor		0.02	W/°C
Operating Junction and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-ambient Max.	R_{thj-a}	45	°C/W

Electrical Characteristics (T_j = 25°C unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV _{DSS}	30	-	-	V	V _{GS} =0, I _D =250Ua
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS} / \Delta T_j$	-	0.037	-	V/°C	Reference to 25°C, I _D =1mA
Gate Threshold Voltage	V _{GS(th)}	1.0	-	3.0	V	V _{DS} =V _{GS} , I _D =250uA
Gate-Source Leakage Current	I _{GSS}	-	-	±100	nA	V _{GS} = ±20V
Drain-Source Leakage Current(T _j =25°C)	I _{DSS}	-	-	25	uA	V _{DS} =30V, V _{GS} =0
Drain-Source Leakage Current(T _j =70°C)		-	-	250	uA	V _{DS} =24V, V _{GS} =0
Static Drain-Source On-Resistance	R _{DS(ON)}	-	-	26	mΩ	V _{GS} =10V, I _D =4A
		-	-	40		V _{GS} =4.5V, I _D =3A
Total Gate Charge ²	Q _g	-	5.4	-	nC	I _D =4A V _{DS} =24V V _{GS} =5V
Gate-Source Charge	Q _{gs}	-	1.3	-		
Gate-Drain ("Miller") Change	Q _{gd}	-	3.6	-		
Turn-on Delay Time ²	T _{d(on)}	-	3.6	-	ns	V _{DS} =15V I _D =1A V _{GS} =10V R _G =3.3Ω R _D =1.9Ω
Rise Time	T _r	-	19.8	-		
Turn-off Delay Time	T _{d(off)}	-	13	-		
Fall Time	T _f	-	3.2	-		
Input Capacitance	C _{iss}	-	260	-	pF	V _{GS} =0V V _{DS} =25V f=1.0MHz
Output Capacitance	C _{oss}	-	144	-		
Reverse Transfer Capacitance	C _{rss}	-	13	-		

Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage ²	V _{SD}	-	-	1.3	V	I _S =2A, V _{GS} =0V, T _j =25°C
Continuous Source Current(Body Diode)	I _S	-	-	4	A	V _D = V _G =0V, V _S =1.3V
Pulsed Source Current(Body Diode) ¹	I _{SM}	-	-	20	A	

Notes: 1. Pulse width limited by safe operating area.

2. Pulse width ≤ 300us, duty cycle ≤ 2%.

Characteristics Curve

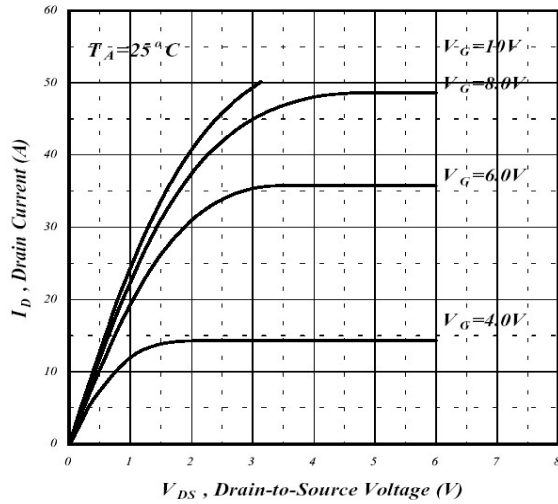


Fig 1. Typical Output Characteristics

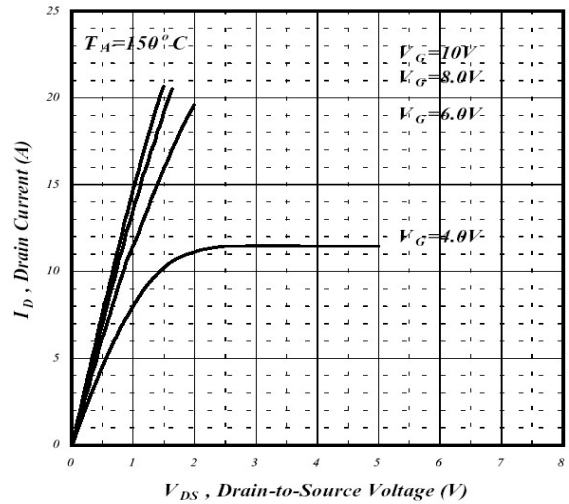


Fig 2. Typical Output Characteristics

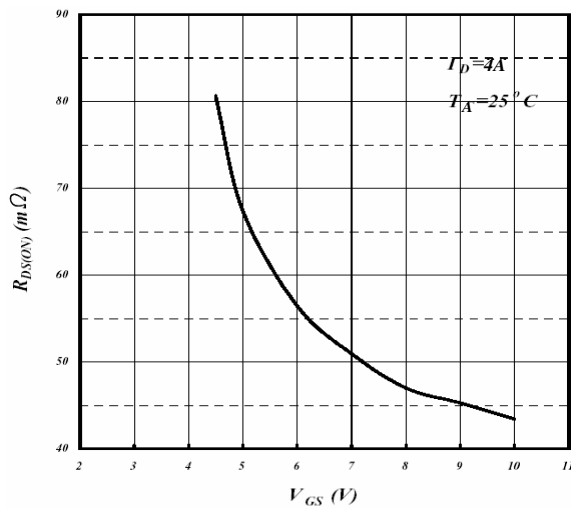


Fig 3. On-Resistance v.s. Gate Voltage

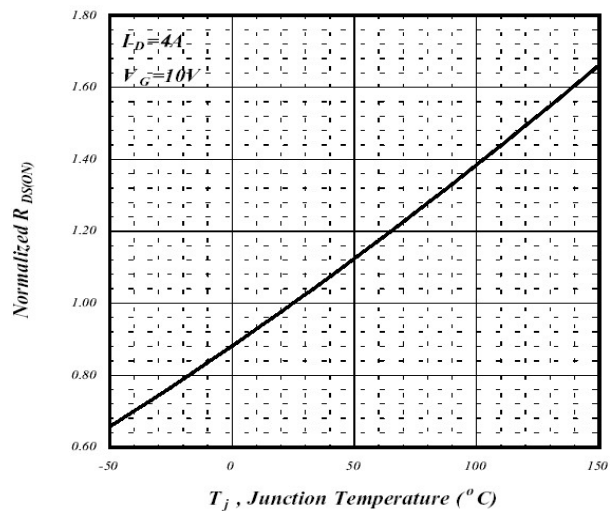


Fig 4. Normalized On-Resistance v.s. Junction Temperature

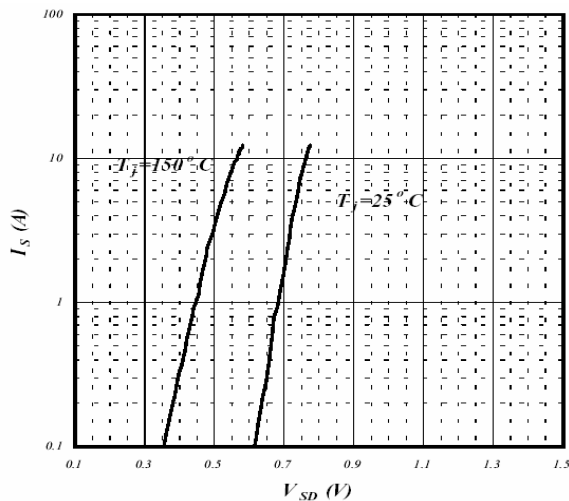


Fig 5. Forward Characteristics of Reverse Diode

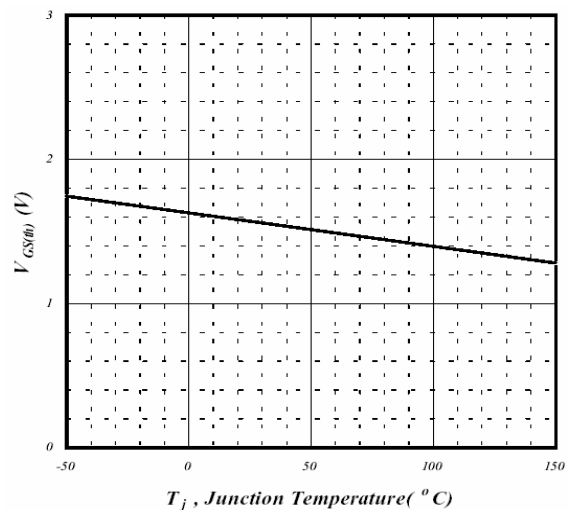


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

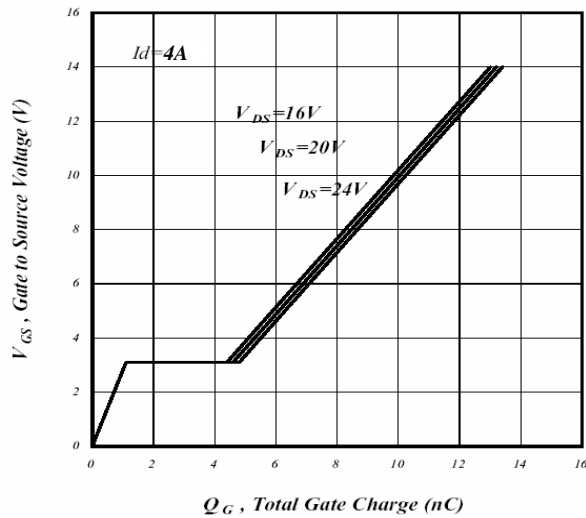


Fig 7. Gate Charge Characteristics

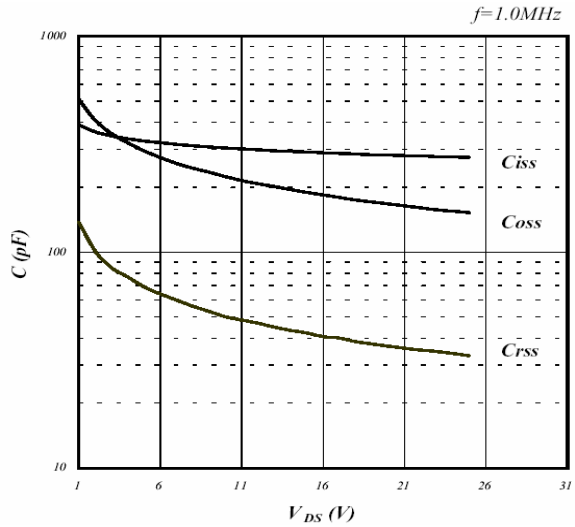


Fig 8. Typical Capacitance Characteristics

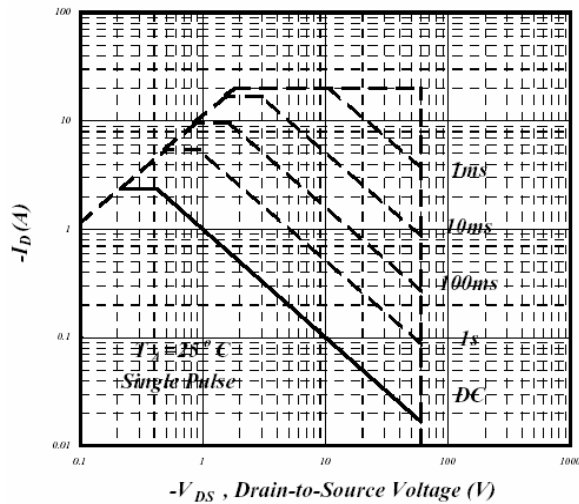


Fig 9. Maximum Safe Operating Area

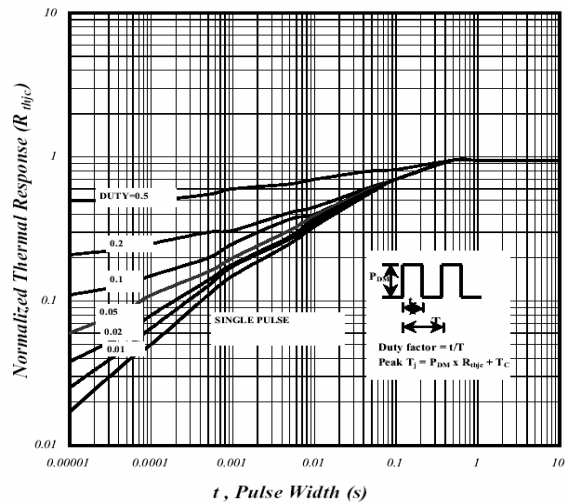


Fig 10. Effective Transient Thermal Impedance

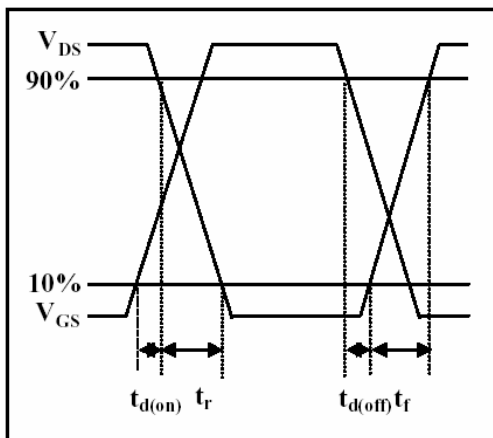


Fig 11. Switching Time Circuit

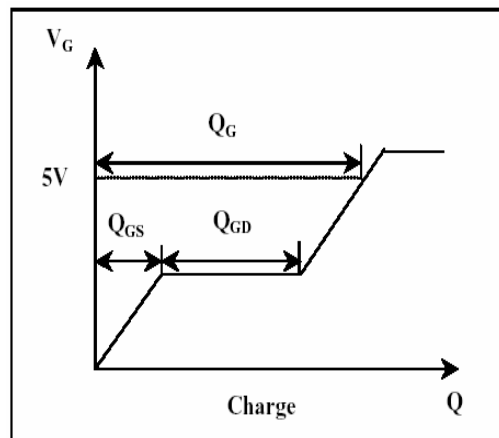


Fig 12. Gate Charge Waveform

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